

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: **Makoto Yoshino, et al.**

Art Unit (parent case): **2829**

Serial No.: **TBD**

Examiner (parent case): **Geyer, Scott B.**

Filed: **Herewith**

Docket: **TI-29448.1**

For: **Semiconductor Package Insulation
Film And Manufacturing Method
Thereof**

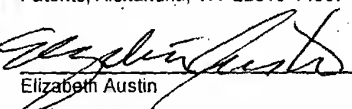
Conf. No.: **TBD**

PRELIMINARY AMENDMENT

Commissioner for Patents

Alexandria, VA 22313-1450

Sir:

<u>MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)</u>	
I hereby certify that on or before this date the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Alexandria, VA 22313-1450.	
 Elizabeth Austin	<u>7/17/2003</u> Date

Please enter the following amendment prior to examination of the instant application.

In the Specification:

Please amend the specification by inserting before the first line the sentence:

-- This is a divisional application of Serial No. 09/909,013, filed 07/19/2001. --